Page 1	of 2 Pages [ ] Ori	ginal [ ] Subs	stitute [ ] S	Supplemental	Atty. Docket:
	Combined Declar	ation for Pat	ent Applic	ation and Power of A	ttorney
As a below-	-named inventor, I hereby d	eclare that:			
My residen	ce, post office address and	citizenship are as si listed below) or an	original, first an	t to my name; and that I believe d joint inventor (if plural names ention entitled	
	FOR BONDING PLASTIC ation of which (check one)	MICRO CHIP			
- 1	[ ] is attached hereto		35 U.S.C. §111 (	on, as	
	(PCT) applicate	in the U.S. under 3 on, PCT/KR2004	<u>/003337;</u> filed ge application re	by entry into the U.S. national son <u>December 17, 2004,</u> eccived U.S. Appln. No.	entry requested o
and was am	ended on			(if applicable).	
	(include dates of	amendments under PC	CT Art. 19 and 34	if PCT) (if applicable).	
amendment known by n I hereby cla inventor's c	referred to above; and I ac ne to be material to patental tim foreign priority benefits	knowledge the duty ility as defined in 3 under 35 U.S.C. §	to disclose to to 7 C.F.R. §1.56. § 119 (a)-(d) an	becification, including the claim the Patent and Trademark Office d 365 (b) of any prior foreign a PCT application which designates	e (PTO) all information pplication(s) for patent
	Application No		Country	Filing Date (MM/DD/YYYY	)
	10-2003-009344	3	KR	12/18/2003	
application	designating a country othe	than the United Son from which forei	tates) or for an	pplication for patent (including inventor's or plant breeder's certained (if left blank, then there ar Filing Date (MM/DD/YY	rtificate, having a filing e none):
I hereby cla		.C. §119(e) of any U	-	pvisional applications listed belog Date (MM/DD/YYYY)	 ow:
		хррисаціон но.		g Date (WIWDD/1111)	
PCT internation U.S.C. §112	ational application(s) design is not disclosed in such U 2, I acknowledge the duty 6 which became available b	tating the U.S., liste S. or PCT internat to disclose to the P	ed below and, in ional application TO all informates	rovisional application(s) or und sofar as the subject matter of ean in the manner provided by the tion which is material to patent pplication and the national or	ach of the claims of thine first paragraph of 3 ability as defined in 3
	Application No.	Filing Date (N	MM/DD/YYYY)	Status (patented, pendir	ng, abandoned)
As a named	d inventor, I hereby appoi	nt the following reg	gistered practitie	oners to prosecute this applica	tion and to transact a

business in the Patent and Trademark Office connected therewith:

All of the practitioners associated with Customer Number 001444

Direct all correspondence to the address associated with Customer Number 001444, which is presently:

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Page 2 of 2 Pages		Atty. Docket:
Title: METHOD FOR BONDING PLASTIC MIC	CRO CHIP	<u> </u>
U.S. Application filed	, Serial No	
PCT Application filed December 17, 2004	Serial No. PCT/KR2004/003337	

The undersigned hereby authorizes the U.S. Attorneys or Agents appointed herein to accept and follow instructions from Kim, Choi & Lim as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. Attorneys or Agents and the undersigned. In the event of a change of the persons from whom instructions may be taken, the U.S. Attorneys or Agents appointed herein will be so notified by the undersigned.

I hereby further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF FIRST INVENTOR	INVENTOR'S SIGNATURE	<del> </del>	n . mn				
Jun Keun CHANG	INVENTOR'S SIGNATURE		DATE 3,/05/06				
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FULL NAME OF SIXTH JOINT INVENTOR	INVENTOR'S SIGNATURE		DATE				
RESIDENCE		CITIZENSHIP					
POST OFFICE ADDRESS							

ALL INVENTORS MUST REVIEW APPLICATION AND DECLARATION BEFORE SIGNING. ALL ALTERATIONS MUST BE INITIALED AND DATED BY ALL INVENTORS PRIOR TO EXECUTION. NO ALTERATIONS CAN BE MADE AFTER THE DECLARATION IS SIGNED. ALL PAGES OF DECLARATION MUST BE SEEN BY ALL INVENTORS.